

Search Notes

Application No.

10/673,459

Examiner

Thao P. Le

Applicant(s)

TSUNODA ET AL.

Art Unit

2818

SEARCHED

Class	Subclass	Date	Examiner
438	106	5/11/2004	T.LE
438	123	5/11/2004	T.LE

INTERFERENCE SEARCHED

Class	Subclass	Date	Examiner
438	107	9/24/2004	T.LE

**SEARCH NOTES
(INCLUDING SEARCH STRATEGY)**

	DATE	EXMR
east search	9/24/2004	
chip, resin sealing plurality chips together, base member having wiring, mold and solder bump.		